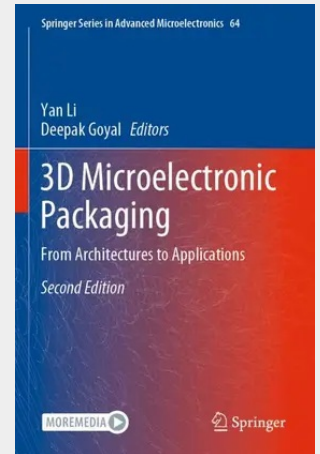


3D Microelectronic Packaging

From Architectures to Applications

This book offers a comprehensive reference guide for graduate students and professionals in both academia and industry, covering the fundamentals, architecture, processing details, and applications of 3D microelectronic packaging. It provides readers an in-depth understanding of the latest research and development findings regarding this key industry trend, including TSV, die processing, micro-bumps for LMI and MMI, direct bonding and advanced materials, as well as quality, reliability, fault isolation, and failure analysis for 3D microelectronic packages. Images, tables, and didactic schematics are used to illustrate and elaborate on the concepts discussed. Readers will gain a general grasp of 3D packaging, quality and reliability concerns, and common causes of failure, and will be introduced to developing areas and remaining gaps in 3D packaging that can help inspire future research and development.

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192,59 €

179,99 € (zzgl. MwSt.)

Lieferfrist: bis zu 10 Tage

Artikelnummer: 9789811570926

Medium: Buch

ISBN: 978-981-15-7092-6

Verlag: Springer

Erscheinungstermin: 24.11.2021

Sprache(n): Englisch

Auflage: 2. Auflage 2021

Serie: Springer Series in Advanced Microelectronics

Produktform: Kartoniert

Gewicht: 955 g

Seiten: 622

Format (B x H): 155 x 235 mm

